

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application.

Please cancel claims 10-12.

LISTING OF THE CLAIMS:

1. (currently amended) An IC card comprising:

(a) a wiring substrate having a front surface and a rear surface;

(b) [[an]] external connecting terminals and wiring arranged over the rear surface of the wiring substrate;

(c) ~~(b) a semiconductor chip disposed~~ a first flash memory chip and a controller chip for the first flash memory chip arranged over the front surface of the wiring substrate and connected electrically to the external connecting terminals through wirings of the wiring substrate; [[and]]

(d) a resin covering the first flash memory chip and the controller chip; and

(e) [[(c)]] a case which covers ~~the wiring substrate and the semiconductor chip~~ the resin in such a manner that the external connecting terminals ~~of the wiring substrate is~~ are exposed,

wherein the case has a first end side near which the external connecting terminals ~~is disposed~~ are arranged and a second end side positioned on an opposite side to the first end side, [[and]]

wherein a planar outline of the wiring substrate is smaller than half of a planar outline of the case,

[[and]] wherein the wiring substrate is entirely disposed in an area of the case closer to the first end side with respect to a middle position between the first and the second end sides, [[.]] and

wherein the case comprises a first case member and a second case member.

2. (currently amended) An IC card according to claim 1, wherein the ~~semiconductor chip~~ is flash memory chip and second memory chip are disposed in an area of the case closer to the first end side with respect to the middle position between the first and the second end sides.

3. (currently amended) An IC card according to claim 1, ~~wherein the case comprises a first case and a second case, one of the first and the second case having a projecting portion in an area other than the area where the wiring substrate is disposed, the other case having a recess~~

~~portion in an area other than the area where the wiring substrate is disposed, the projecting portion being fitted in the recess portion so as to connect the first and the second case with each other.~~

wherein, in an area of the case closer to the second end side with respect to a middle position, the first case member has a recess portion, and

wherein, in an area of the case closer to the first end side with respect to a middle position, the second case member has a projecting portion being fitted in the recess portion so as to connect the first case member and the second case member with each other.

4. (original) An IC card according to claim 3, wherein a tip-side inner periphery portion of the recess portion and a tip-side outer periphery portion of the projecting portion are chamfered.

5. (currently amended) An IC card according to claim 3, wherein the recess portion and the projecting portion have an aligning function for ~~self-alignmentwise~~ aligning planar positions of the first case member and the second case member when both said ~~eases~~ case members are superimposed one over the other.

6. (currently amended) An IC card according to claim 3, wherein the projecting portion ~~formed over the first or the second case~~ has a function for fixing the second case member ~~formed with the projecting portion~~ to a carrier temporarily.

7. (currently amended) An IC card according to claim 1, further comprising a movable switch,

~~wherein the case comprises a first case and a second case, and~~ in the first case member or the second case member, a mechanism for holding the movable switch is provided in an area other than the area where the wiring substrate is disposed.

8. (currently amended) An IC card according to claim 1, further comprising a movable switch, wherein ~~the case comprises a first case and a second case, and~~ in the first case member or the second case member, a click mechanism for the movable switch is provided in an area other than the area where the wiring substrate is disposed.

9. (currently amended) An IC card according to claim 1, further comprising a movable switch,

~~wherein the case comprises a first case and a second~~
case, and means for fixing the first case member and the
second case member to a carrier temporarily are provided in
areas of the first case member and the second case member
other than the area where the wiring substrate is disposed.

Claims 10-20 (canceled).

21. (new) An IC card according to claim 1,
wherein the external connecting terminals include a
data terminal, a ground voltage supply terminal and a clock
signal input terminal.

22. (new) An IC card according to claim 1,
wherein a planar size of said memory card is set to
24mm x. 32mm.

23. (new) An IC card according to claim 1,
wherein a thickness of said memory card is set to 2.1
mm.

24. (new) An IC card according to claim 1,
wherein the first flash memory chip is of larger size
than the controller chip.

25. (new) An IC card according to claim 1, further comprising:

a second flash memory chip, and

wherein the resin covers said controller chip and the first and second flash memory chips.

26. (new) An IC card according to claim 25,

wherein the second flash memory chip is mounted over the first flash memory chip.

27. (new) An IC card according to claim 1,

wherein the external connecting terminals are arranged in first and second rows,

wherein the external terminals of the first row is shifted from the external terminals of the second row in a first direction in which the external connecting terminals are arranged, and

wherein, in a second direction perpendicular to the first direction, the external connecting terminals of the second row are arranged behind a region between the external connecting terminals of the first row.

28. (new) An IC card according to claim 1,
wherein the external connecting terminals include data
terminals corresponding to eight bits and are provided as
thirteen in total.

29. (new) An IC card comprising:
a substrate having a front surface and a rear surface;
a first flash memory chip arranged over the front
surface of the substrate;
a controller chip for the first flash memory chip
arranged over the front surface of the substrate;
a resin covering the first flash memory chip and the
controller chip;
a case defining dimensions of the integrated circuit
card, and the case covering the resin and the substrate; and
external connecting terminals arranged over the rear
surface of the substrate and exposed from the case;
wherein, in a direction of a long side of the case, a
length of the substrate is smaller than a length of one half
of the case, and
wherein the case comprises has
a first case member covering the front the
surface of the substrate;

a second case member covering the rear surface of the substrate; and

a first area and a second area, with the substrate being entirely disposed in the first area; and

wherein, in the first case member and the second case member, a mechanism for holding a movable switch is provided in the second area.

30. (new) An IC card according to claim 29, wherein the external connecting terminals include a data terminal, a ground voltage supply terminal and a clock signal input terminal.

31. (new) An IC card according to claim 29, wherein a planar size of said memory card is set to 24mm × 32mm.

32. (new) An IC card according to claim 29, wherein a thickness of said memory card is set to 2.1 mm.

33. (new) An IC card according to claim 29,
wherein the first flash memory chip is of larger size
than the controller chip.

34. (new) An IC card according to claim 29, further
comprising:

a second flash memory chip,
wherein the resin covers said controller chip, the
first flash memory chip, and the second flash memory chip.

35. (new) An IC card according to claim 34,
wherein the second flash memory chip is mounted over
the first flash memory chip.

36. (new) An IC card according to claim 29,
wherein the external connecting terminals are arranged
in first and second rows,

wherein the external terminals of the first row are
shifted from the external terminals of the second row in a
first direction in which the external connecting terminals
are arranged, and

wherein, in a second direction perpendicular to the
first direction, the external connecting terminals of the

second row are arranged behind a region between the external connecting terminals of the first row.

37. (new) An IC card according to claim 29, wherein the external connecting terminals include data terminals corresponding to eight bits and are provided as thirteen in total.